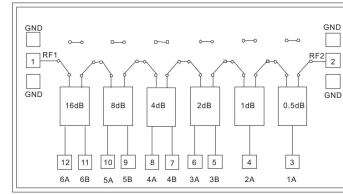


### Performance

- Frequency: 0.1-8GHz
- Insertion loss: 2.5dB
- Attenuation range: 0.5~31.5dB
- Handling Power: +24dBm
- Chip size: 2.40\*1.00\*0.10mm

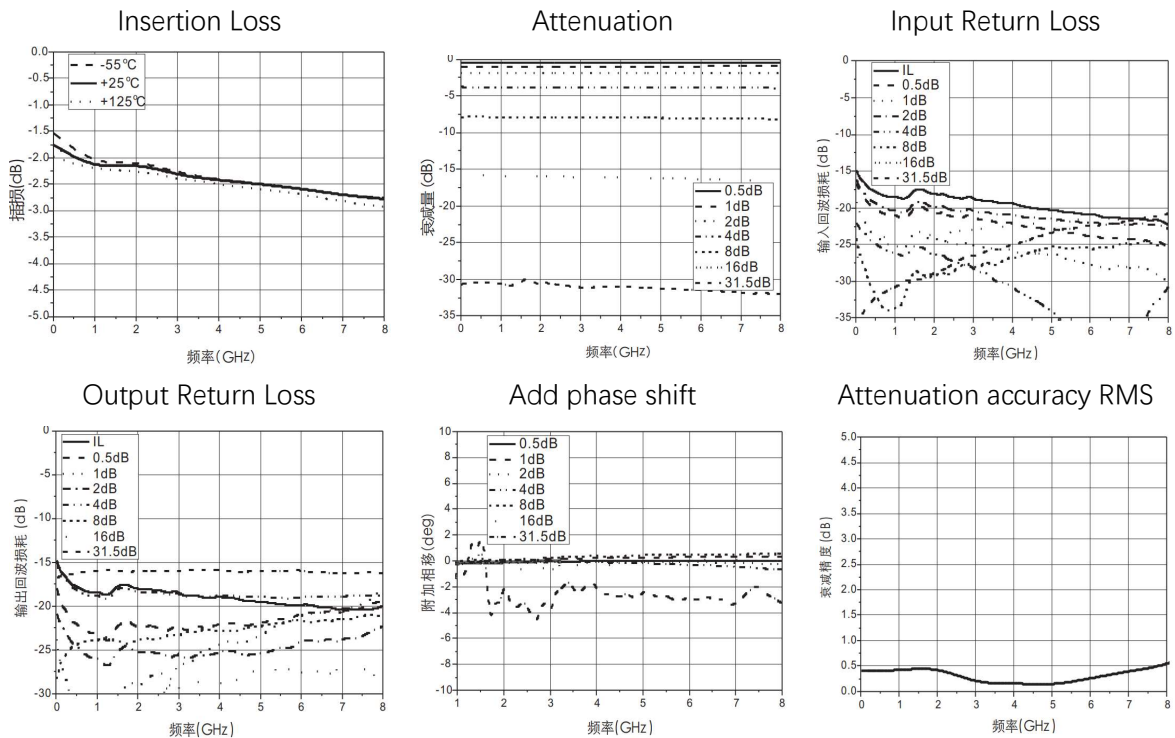
### Functional Diagram



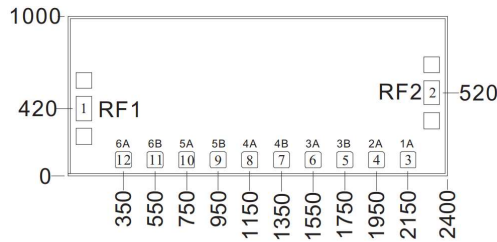
### Electrical Specifications (Ta=+25°C, 0/-5V control, 50Ω system)

Parameter	Test Frequency	Min	Typical	Max	Unit
Insertion Loss	0.1GHz-8GHz	-	2.5	3.5	dB
Attenuation Range	0.1GHz-8GHz	0.5	-	31.5	dB
Return Loss (RF1, RF2)	0.1GHz-8GHz	-	15	-	dB
Attenuation Accuracy RMS	0.1GHz-8GHz	-	0.5	1	dB
Add phase shift	0.1GHz-8GHz	-	±5	-	Deg
Input P1dB	0.1GHz-8GHz	-	20	-	dBm
Input IP3	0.1GHz-8GHz	-	35	-	dBm
Switch time	0.1GHz-8GHz	-	10	-	ns

### Test Curves (Two bonding lines which are Ø25um, 400um length applied to the RF ports)



**Outline Size**



**Note:**

1. Unit:  $\mu\text{m}$
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated:  
1,2 size:  $150 \times 100 \mu\text{m}$ , 3~12 size:  $100 \times 100 \mu\text{m}$
5. Don't bonding on thru holds
6. Tolerance:  $\pm 50 \mu\text{m}$

**Truth Table**

0.5dB	1dB	2dB		4dB		8dB		16dB		Attenuation
1A	2A	3A	3B	4A	4B	5A	5B	6A	6B	Status
1	1	1	0	1	0	1	0	1	0	Reference
0	1	1	0	1	0	1	0	1	0	0.5dB
1	0	1	0	1	0	1	0	1	0	1dB
1	1	0	1	1	0	1	0	1	0	2dB
1	1	1	0	0	1	1	0	1	0	4dB
1	1	1	0	1	0	0	1	1	0	8dB
1	1	1	0	1	0	1	0	0	1	16dB
0	0	0	1	0	1	0	1	0	1	31.5dB

**Bonding Pads Description**

Number	Symbol	Description
1,2	RF1, RF2	RF ports, 50 Ohm, external capacitor needed
3,4,6,8,10,12	CTRL A	Control port
5,7,9,11	CTRL B	Control port
-	GND	Bottom must be grounded

**Control Voltage**

Status	Bias Condition
Low	0 ~ -0.2V
High	-3 ~ -5V

**Absolute Max Ratings**

RF Input Power (Vctl = -5V)	+24dBm
Control Voltage Range (A, B)	+0.5V ~ -7.0V
Junction Temperature	175°C
Storage Temperature	-65 ~ +150°C
Operating Temperature	-55 ~ +125°C
Static Protection Grade (HBM)	Class 1A



